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# INTERNATIONAL STANDARD



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**Semiconductor devices – Micro-electromechanical devices –  
Part 28: Performance testing method of vibration-driven MEMS electret energy  
harvesting devices**

INTERNATIONAL  
ELECTROTECHNICAL  
COMMISSION

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## INTERNATIONAL ELECTROTECHNICAL COMMISSION

### SEMICONDUCTOR DEVICES – MICRO-ELECTROMECHANICAL DEVICES –

#### Part 28: Performance testing method of vibration-driven MEMS electret energy harvesting devices

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Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

This document has been drafted in accordance with the ISO/IEC Directives, Part 2.

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**SEMICONDUCTOR DEVICES –  
MICRO-ELECTROMECHANICAL DEVICES –**

**Part 28: Performance testing method of vibration-driven  
MEMS electret energy harvesting devices**

**1 Scope**

This part of IEC 62047 specifies terms and definitions, and a performance testing method of vibration driven MEMS electret energy harvesting devices to determine the characteristic parameters for consumer, industry or any application.

This document applies to vibration driven electret energy harvesting devices whose electrodes with a gap below 1 000  $\mu\text{m}$  are covered by dielectric material with trapped charges and are fabricated by MEMS processes such as etching, photolithography or deposition.

**2 Normative references**

There are no normative references in this document.